

RoHS 豁免条令总结 (2006-11-01)
(英文原版条令，中文翻译仅供参考)

2002/95/EC

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
小型日光灯中的汞含量不得超过5毫克/灯；
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
一般用途的直管日光灯中的汞含量不得超过：Halophosphate—10 mg 盐磷酸盐—10毫克；
Triphosphate with normal lifetime—5 mg 一般灯管中的三磷酸盐—5毫克；
Triphosphate with long lifetime—8 mg 超长寿命灯管中的三磷酸盐—8毫克；
3. Mercury in straight fluorescent lamps for special purposes.
特殊用途的直管日光灯中的汞含量；
4. Mercury in other lamps not specifically mentioned in the Annex.
本附录中未特别提及的其它照明灯中的汞含量；
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
阴极射线管、电子部件和发光管的玻璃内的铅含量；
6. Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminum containing up to 0.4% lead by weight and as a copper alloy containing up to 4% lead by weight.
铅作为合金元素在钢合金中达0.35%，铝合金中达0.4%和铜合金中达4%；
7. Lead in high melting temperature type solders (ie: tin-lead solders alloys containing more than 85% lead),
高熔点类型焊料中的铅（即：锡铅焊料合金含铅超过85%）；
lead in solders for servers, storage and storage array systems (exemption granted until 2010),
用于服务器、存储器和存储阵列系统的焊料中的铅（豁免准予至2010年）；
lead in solders for network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunication,
用于通讯网络设备、电闸、信号发送和电送网络基础设备焊料中的铅；
Lead in electronic ceramic parts (e.g. piezoelectronic devices).
电子陶瓷零部件中的铅（例如：压电陶瓷装置）(2005/747/EC 中有修改)
8. Cadmium plating except for applications banned under Directive 91/338/EEC (OJ No. L 186, 12 July 1991, p. 59) amending Directive 76/769/EEC (OJ No. L262, 27 September 1976, p. 201) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
根据修改关于限制特定危险物质和预制品销售和使用的第76/769/EEC号指令的第91/338/EEC号指令禁止以外的镉电镀；（2005/747/EC中有修改）
9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
在吸收式电冰箱中作为碳钢冷却系统防腐剂的六价铬；
10. Within the procedure referred to in Article 7(2), the Commission shall evaluate the applications for:
根据在第7（2）条中提及的程序，欧盟委员会应评价以下方面的应用：
Deca BDE, 十溴二苯醚
mercury in straight fluorescent lamps for special purposes,
特殊用途的直管日光灯中的汞；
lead in solders for servers, storage and storage array systems, network infrastructure equipment for

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switching, signalling, transmission as well as network management for telecommunications (with a view to setting a specific time limit for this exemption), and

以下用途中所使用的焊料中的铅：服务器、存储器和存储阵列系统、用于通讯网络设备、电闸、信号发送和电送网络基础设施（旨在设定本指令豁免部分的特定截止时间）；

light bulbs. 灯泡。

2005/717/EC

9a. Deca BDE in polymeric applications.

十溴二苯醚在聚合物中的使用

9b. Lead in lead-bronze bearing shells and bushes.

青铜轴承外壳和衬套中的铅

2005/747/EC

7. Lead in high melting temperature type solders (ie: lead-based alloys containing more than 85% lead) , (对2002/95/EC的修改)

高熔点类型焊料中的铅（即：含铅超过85%的铅合金）；

lead in solders for servers, storage and storage array systems , network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunication. (对2002/95/EC的修改)

用于服务器、存储器和存储阵列系统以及有关通讯网络设备中信号的交换、发送、传输和电送网络基础设施焊料中的铅；

8. Cadmium and its compounds in electrical contacts and cadmium plating

except for applications banned under Directive 91/338/EEC (OJ No. L 186, 12 July 1991, p. 59)

amending Directive 76/769/EEC (OJ No. L262, 27 September 1976, p. 201) relating to restrictions on the marketing and use of certain dangerous substances and preparations. (对2002/95/EC的修改)

电触头中镉及镉化合物的应用，以及根据修改关于限制特定危险物质和预制品销售和使用的第76/769/EEC号指令的第91/338/EEC号指令禁止以外的镉电镀；

11. Lead used in compliant pin connector systems.

连接器系统顺应针中使用的铅；

12. Lead as a coating material for the thermal conduction module c-ring.

C型环导热模块涂层材料中的铅；

13. Lead and cadmium in optical and filter glass.

光学玻璃及滤光玻璃中所用的铅及镉；

14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.

用以连接插脚和微处理器封装的复合焊料（两个元素以上）中的铅，并且铅的浓度在80-85%之间；

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

集成电路倒装芯片封装中半导体铸模和载波器的焊料中的铅；

2006/310/EC

16. Lead in linear incandescent lamps with silicate coated tubes.

线形白炽灯硅酸盐涂层灯管中的铅；

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17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications.

在专业复印应用的高强度气体放电灯（HID）中作为发光介质的卤化铅

18. Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi_2O_5 :Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba) MgSi_2O_7 :Pb).

当放电灯作为含磷（如 BSP (BaSi_2O_5 :Pb)）的仿日晒灯，或作为含磷（如 SMS ((Sr,Ba) MgSi_2O_7 :Pb)）的重氮复印、平版印刷、捕虫器、光化学和食品加工过程的专用灯时，放电灯荧光粉中作为触媒剂的铅含量在 1%或以下；

19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL).

紧凑型节能灯中作为特定成分PbBiSn-Hg 和 PbInSn-Hg为主要汞齐合金以及 PbSn-Hg为辅助汞齐合金中的铅；

20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD).

液晶显示器中用于连接平面荧光灯前后基质的玻璃中的氧化铅；

2006/690/EC、2006/691/EC、2006/692/EC

21. Lead and cadmium in printing inks for the application of enamels on borosilicate glass.

硼硅酸盐玻璃表面瓷釉上印刷油墨中的铅与镉；

22. Lead as impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communications systems.

光纤通讯系统稀土铁石榴石法拉第旋转器中作为杂质的铅；

23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames.

小螺距零部件表面抛光中的铅（螺距超过0.65mm的连接器中的铅、没有镍铁铅框连接器中的铅、没有铜铅框连接器中的铅不在豁免范围内）；

24. Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors.

通孔盘状及平面阵列陶瓷多层电容器焊料所含的铅；

25. Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements; notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and frit ring as well as in print pastes.

等离子显示屏(PDP)及表面传导式电子发射显示器(SED)的构件所用的氧化铅，比如：玻璃前后介电层、汇流电极、黑条纺（用于彩色显象管）、地址电极、障壁（阻隔壁）、密封釉料、环状釉料以及油墨中的氧化铅；

26. Lead oxide in the glass envelope of Black Light Blue (BLB) lamps.

布莱克蓝灯（蓝黑灯管）（BLB）玻璃封套中的氧化铅；

27. Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 dB SPL and above) loudspeakers.

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用作高性能（长时间在125分贝或以上）扬声器的传感器中焊料的铅合金；

28. Hexavalent chromium in corrosion preventive coatings of unpainted metal sheetings and fasteners used for corrosion protection and Electromagnetic Interference Shielding in equipment falling under category three of Directive 2002/96/EC (IT and telecommunications equipment). Exemption granted until 1 July 2007.

在2002/96/EC指令第三条中规定IT及电信设备中，为了防腐蚀及电磁干扰屏蔽的用于没有上涂料的金属板和按钮上防腐蚀性保护层中的六价铬，准予豁免的截止日期为2007年7月1日；

29. Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC (OJ L 326, 29.12.1969, p. 36. Directive as last amended by 2003 Act of Accession.)

水晶玻璃中铅含量的限值（参考欧盟指令69/493/EEC附件1、2、3、4类，最后修改于2003法案

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地 址：深圳市福田区竹子林益华大厦北 710（深南大道竹子林地铁口 B2 出口）

邮政编码：518040

电 话：86-755-83187996（周小姐）

电 话：86-755-83709189（谢小姐）

电 话：86-755-81939926

手 机：（0）13824328299（余先生）

传 真：86-755-83709189

网 址：www.ebotech.cn www.emclab.net

邮 箱：ebotech@163.com yuhaoqun@ebotech.cn

M S N：yuhaoqun@hotmail.com

QQ: 9576459

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